

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-8 (canceled).

Claim 9 (original): A multilayer substrate including a built-in chip-type electronic component comprising:

a laminate including a plurality of laminated dielectric layers in a lamination direction;

a chip-type electronic component disposed in the laminate and having a terminal electrode; and

a via conductor disposed in the dielectric layers in the lamination direction; wherein

the terminal electrode of the chip-type electronic component is connected to at least one of upper and lower end surfaces of the via conductor, and a connection step is provided in the via conductor.

Claim 10 (original): The multilayer substrate including the built-in chip-type electronic component according to Claim 9, wherein the dielectric layers are ceramic layers, the laminate is a ceramic laminate including a plurality of the ceramic layers, and the chip-type electronic component includes a ceramic sintered body defining an element body.

Claim 11 (original): The multilayer substrate including the built-in chip-type electronic component according to Claim 10, wherein the ceramic layers are composed of a low-temperature co-fired ceramic material, and the via conductor is composed of a conductor material including silver or copper as a main component.

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Claim 12-16 (canceled).